

ABSTRACT

A method and device are provided to realize a structure in which different kinds of chips are three-dimensionally mounted while allowing for proper heat dissipation. A semiconductor package PK12 in which stacked semiconductor chips 33a and 33b are wire-connected is stacked on a semiconductor package PK11 in which a semiconductor chip 23 is mounted by anisotropic conductive film (ACF) bonding. A carrier substrate 31 is mounted on a carrier substrate 21 in a state where the reverse face of the semiconductor chip 23 is exposed.